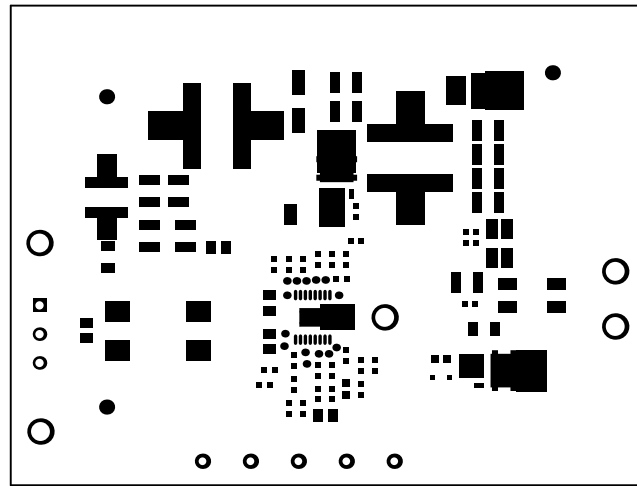
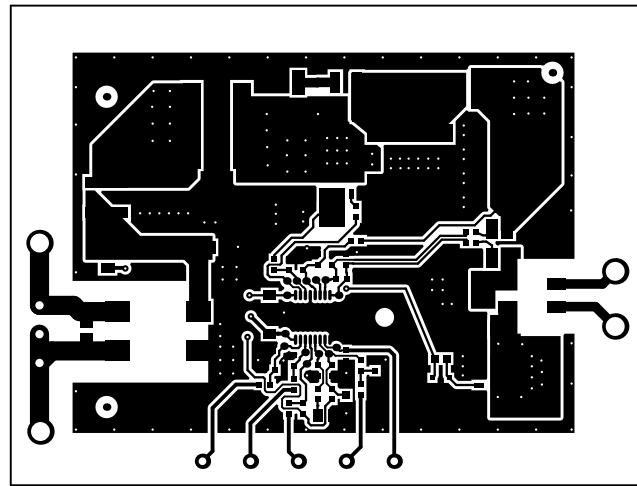


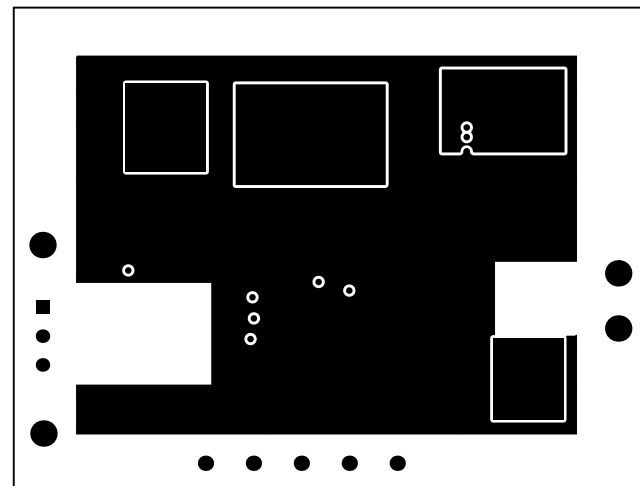
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/30/2017 3:47:35 PM	TEXAS INSTRUMENTS	



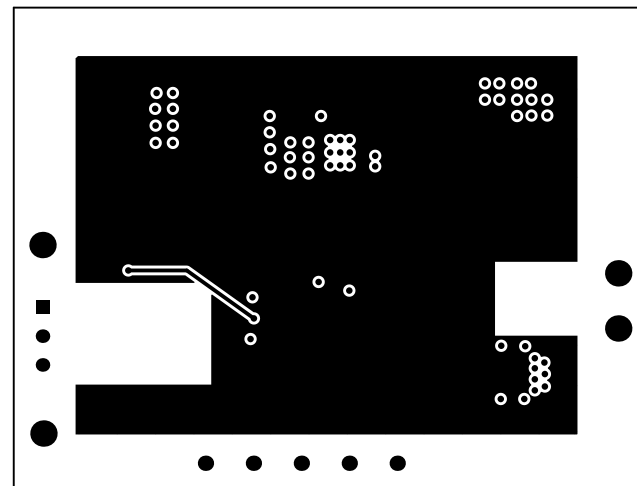
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/30/2017 3:47:36 PM	TEXAS INSTRUMENTS	



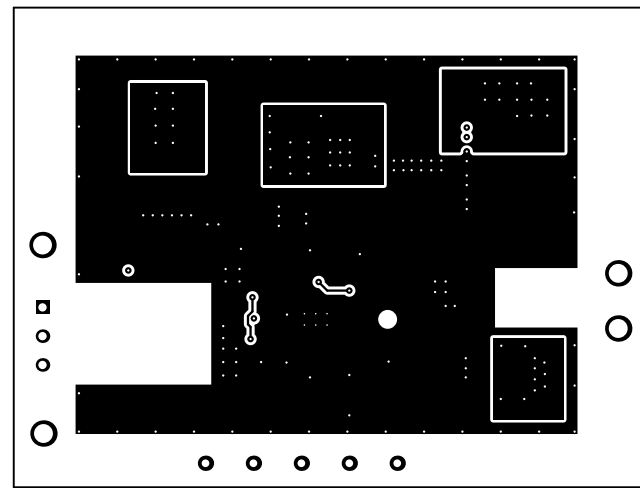
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/30/2017 3:47:37 PM	TEXAS INSTRUMENTS	



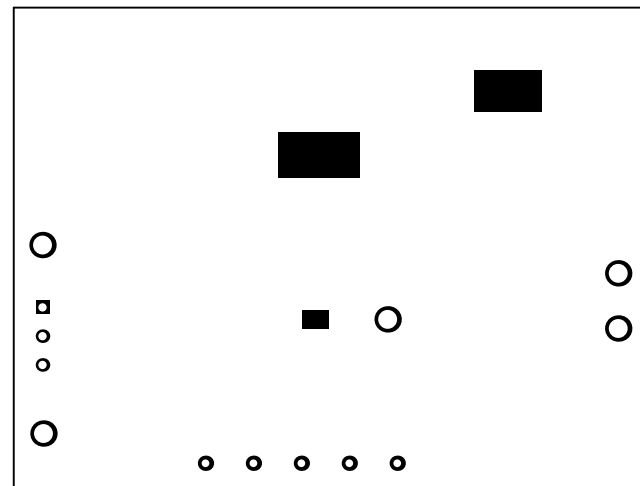
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 6/30/2017 3:47:38 PM	TEXAS INSTRUMENTS	



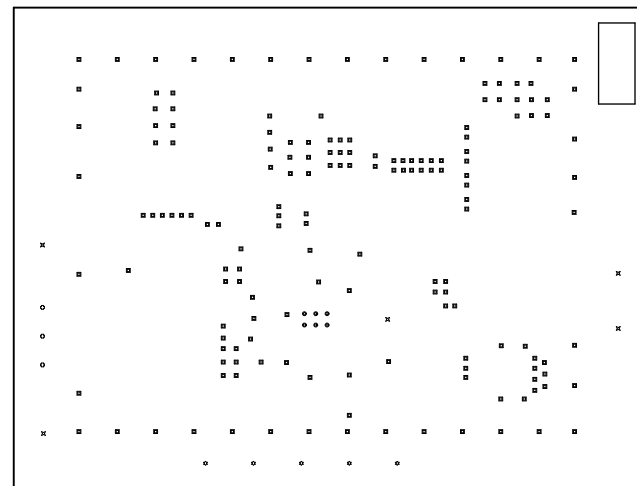
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 6/30/2017 3:47:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 6/30/2017 3:47:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/30/2017 3:47:41 PM	TEXAS INSTRUMENTS	

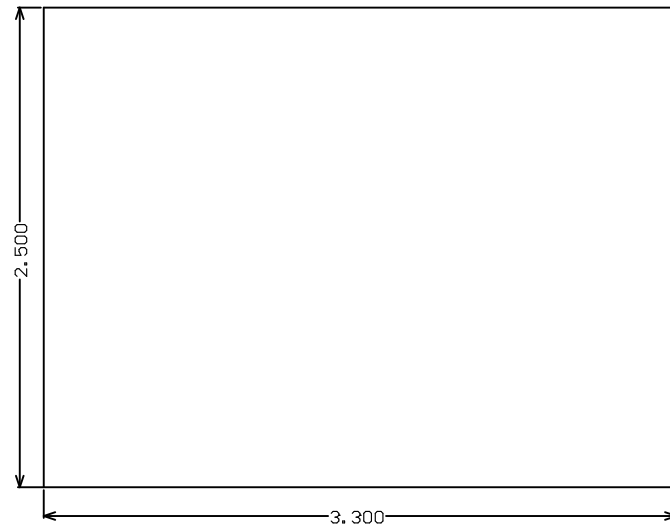


PLACE MFGRS LOGO, UL FLAMMABILITY RATING, Tg TEMP, AND DATE CODE HERE BOTTOM SIDE

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊙	6	8.00mil (0.203mm)	PTH	Round
⊠	162	12.00mil (0.305mm)	PTH	Round
⊛	5	40.00mil (1.016mm)	PTH	Round
⊞	3	43.31mil (1.100mm)	PTH	Round
⊘	5	98.43mil (2.500mm)	PTH	Round
	181 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/30/2017 3:47:42 PM	TEXAS INSTRUMENTS	





ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15027	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/30/2017 3:47:43 PM	TEXAS INSTRUMENTS	

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